

IN THE CLAIMS

Please amend the claims as follows:

1 – 26. (Canceled)

27. (Currently Amended) A ~~manufacturing~~ method of manufacturing a module component comprising:

an inserting step of inserting a chip component in a molding die;

a primary molding step of filling the molding die with resin with [[an]] a first end electrode of the chip component exposed;

a peeling step of peeling the molding die at a side of inserting the chip component;

a secondary molding step of filling the molding die with resin with [[an]] a second end electrode of the chip component; and

a forming step of forming a circuit wiring on one side or both sides of a molded element molded with resin, wherein the chip component is disposed according to a specified rule, and the chip component ~~are is~~ molded with the resin ~~to compose a desired circuit.~~

28. (Currently Amended) A ~~manufacturing~~ method according to claim 27, wherein the chip component is disposed in a specified position according to a matrix, ~~and the chip component of a specific value is molded with the resin to compose a desired circuit.~~

29. (Currently Amended) A ~~manufacturing~~ method according to claim 28, wherein a dummy component having a same size as the chip component is inserted at a position where the chip component is not inserted according to the matrix.

30. (Canceled)

31. (Currently Amended) A ~~manufacturing~~ method of claim 28, wherein the matrix has N aligned rows and M aligned columns, N being equal to or greater than 3, and M being equal to or greater than 3.